Specification of Thermoelectric Module

TEC1-12702

Description

The 127 couples, 40 mm × 40 mm size module is a single stage module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

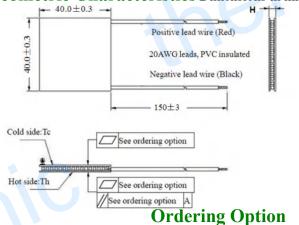
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

		1	T.	
Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	16	16.6	Voltage applied to the module at DT _{max}	
I _{max} (amps)	3.1	3.1	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	32.3	36.5	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (ohms)	4.05	4.45	The module resistance is tested under AC	
Tolerance (%)	10%		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217° C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

AIO: Alumina white 96%

2. Aluminum Nitride (AlN)

2. Metalized

Naming for the Module

Suffix	Thickness	Flatness/	Lead wire length(mm)			
	(mm)	Parallelism (mm)	Standard/Optional length			
TF	0:4.5±0.1	0:0.08/0.08	150±3/Specify			
TF	1:4.5±0.03	1:0.03/0.03	150±3/Specify			
Eg. TF01: Thickness 4.5 ± 0.1 (mm) and Flatness $0.03/0.03$ (mm)						

Ceramics Flatness/ Parallelism Sealant Solder TES1-12702-T100-NS-TF01-AlO T100: BiSn (Tmelt=138°C)

TEC1-12702- X-X-X-X

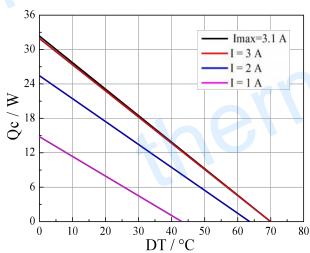
NS: No sealing

TF01: Thickness ±0.1 (mm) and Flatness/Parallelism 0.025/0.025(mm)

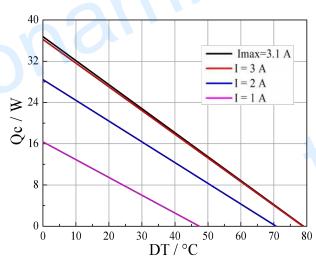
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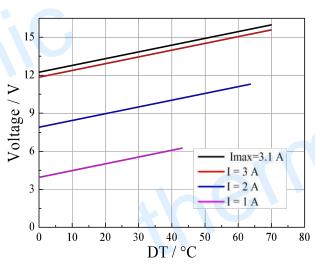


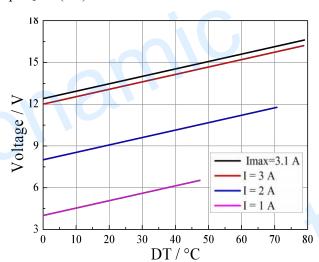


Performance Curves at Th=50 °C

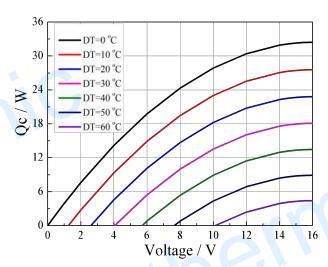


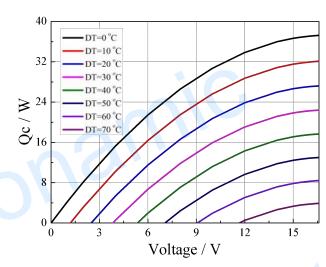
Standard Performance Graph Qc= f(DT)





Standard Performance Graph $V= f(\Delta T)$





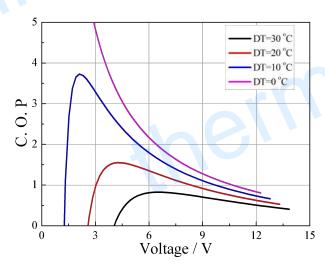
Standard Performance Graph Qc = f(V)

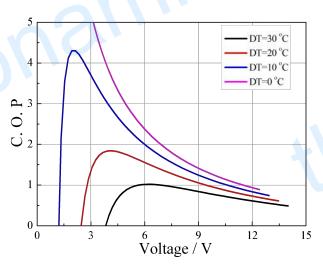
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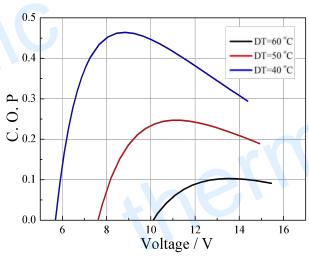
Performance Curves at Th=27 °C

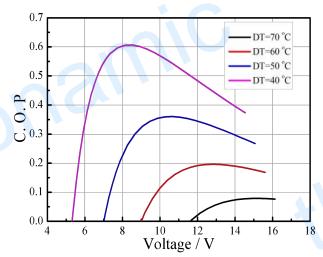
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC